# Preface

It is our pleasure to welcome you to the 2013 International Conference on Mechatronics and Semiconductor Materials (ICMSCM 2013) in Xi'an, China. A major goal and feature of it is to bring academic scientists, engineers, industry researchers together to exchange and share their experiences and research results, and discuss the practical challenges encountered and the solutions adopted.

We hope you will have a technically rewarding experience, and use this occasion to meet old friends and make many new ones. Don't miss the opportunity to explore in Xi'an, China. And don't forget to take a sample of the many and diverse attractions in the rest of the China.

ICMSCM 2013 promises to be both stimulating and informative with a wonderful array of keynote and invited speakers from all over the world. Delegates will have a wide range of sessions to choose from and will have a difficult decision in deciding which sessions to attend.

This book covers these topics: Mechanics, Electronics and Industrial Informatics. We hope your experience with ICMSCM 2013 is a fruitful and long lasting one. With your support and participation, the conference will continue its success for a long time.

We would like to thank the organization staff, the members of the program committees and reviewers. They have worked very hard in reviewing papers and making valuable suggestions for the authors to improve their work. We also would like to express our gratitude to the external reviewers, for providing extra helps in the review process, and the authors for contributing their research result to the conference. Special thanks go to TTP Publisher.

We wish all attendees of t ICMSCM 2013 an enjoyable scientific gathering in Xi'an, China. We look forward to seeing all of you next year at the conference.

The Editors